

ABSTRACT OF THE DISCLOSURE

A resist film forming method including a resist coating step, comprising steps of rising by a capillary phenomenon a
5 coating liquid stored below the coating surface of a substrate held facing-downward, bringing the rised coating liquid into contact with the coating surface via a nozzle, and scanning the nozzle along the coating surface of the substrate thereby coating the resist film on the coating surface of the substrate,
10 wherein said method further including a step of drying the coated resist film by moving the substrate at a predetermined speed with the coating surface of the substrate facing downward.